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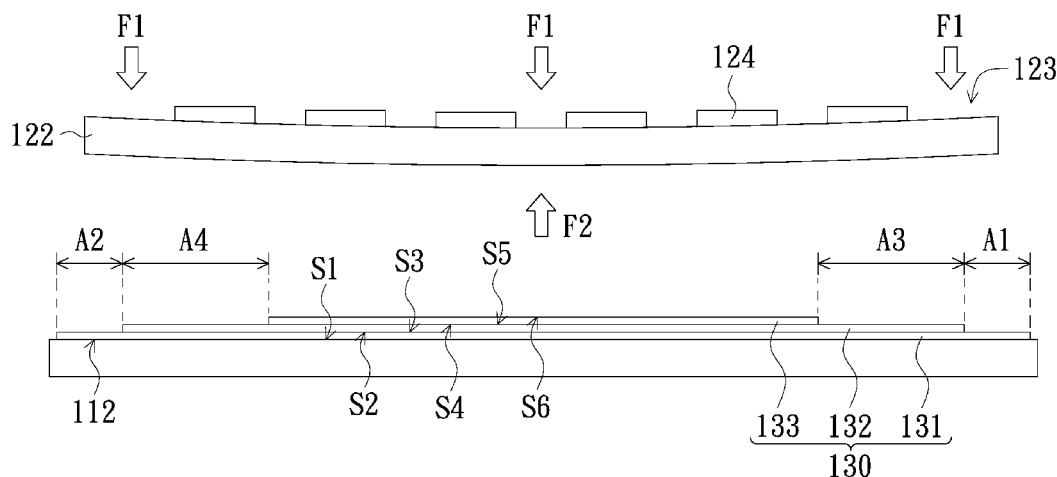
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(57) **ABSTRACT**

A display apparatus includes a frame, a panel module and an adjusting pad. The frame has a supporting surface, and the panel module includes a substrate and a plurality of chips. The substrate is disposed on the supporting surface and has a bonding region at a side of the substrate. The chips are disposed on the bonding region, wherein the chips and the supporting surface are located at two opposite surfaces of the substrate. The adjusting pad is disposed between the supporting surface and the bonding region, and the thickness of the adjusting pad is gradually reduced from a center portion of the adjusting pad toward two sides of the adjusting pad. Another display apparatus, in which a frame and an adjusting pad are integrated into one piece, is provided.

12 Claims, 5 Drawing Sheets

Field of Classification Search
CPC ... H05K 5/0017; H05K 7/14; H05K 13/0015;
H05K 5/0043; G02F 1/133308; G02F



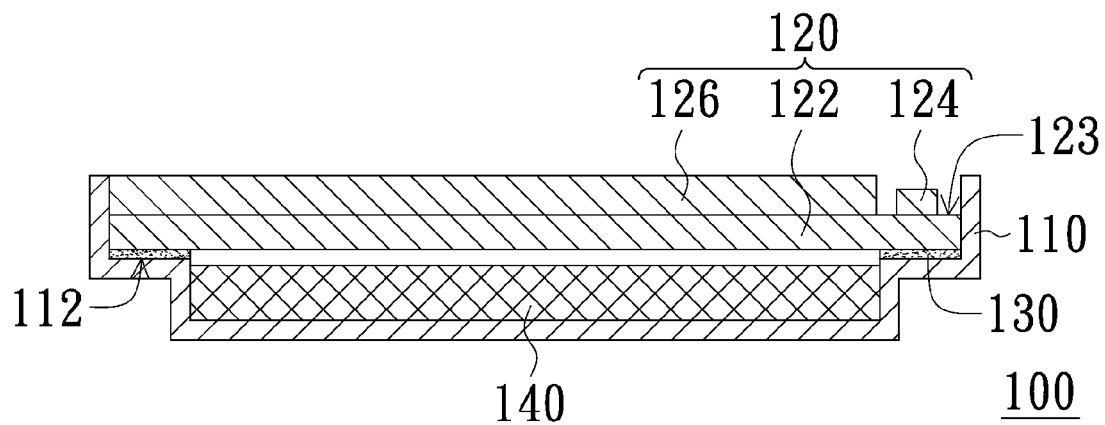


FIG. 1

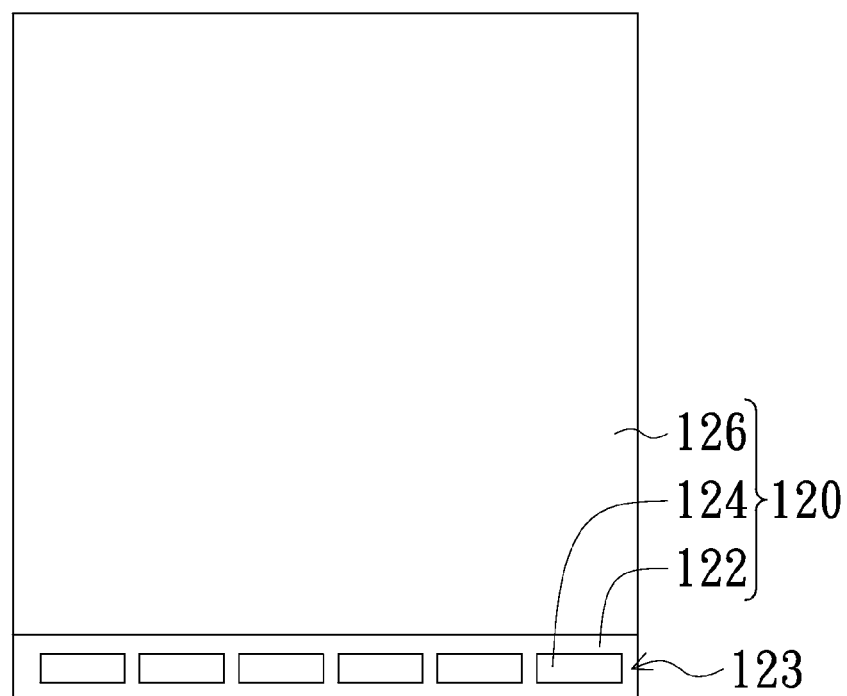


FIG. 2

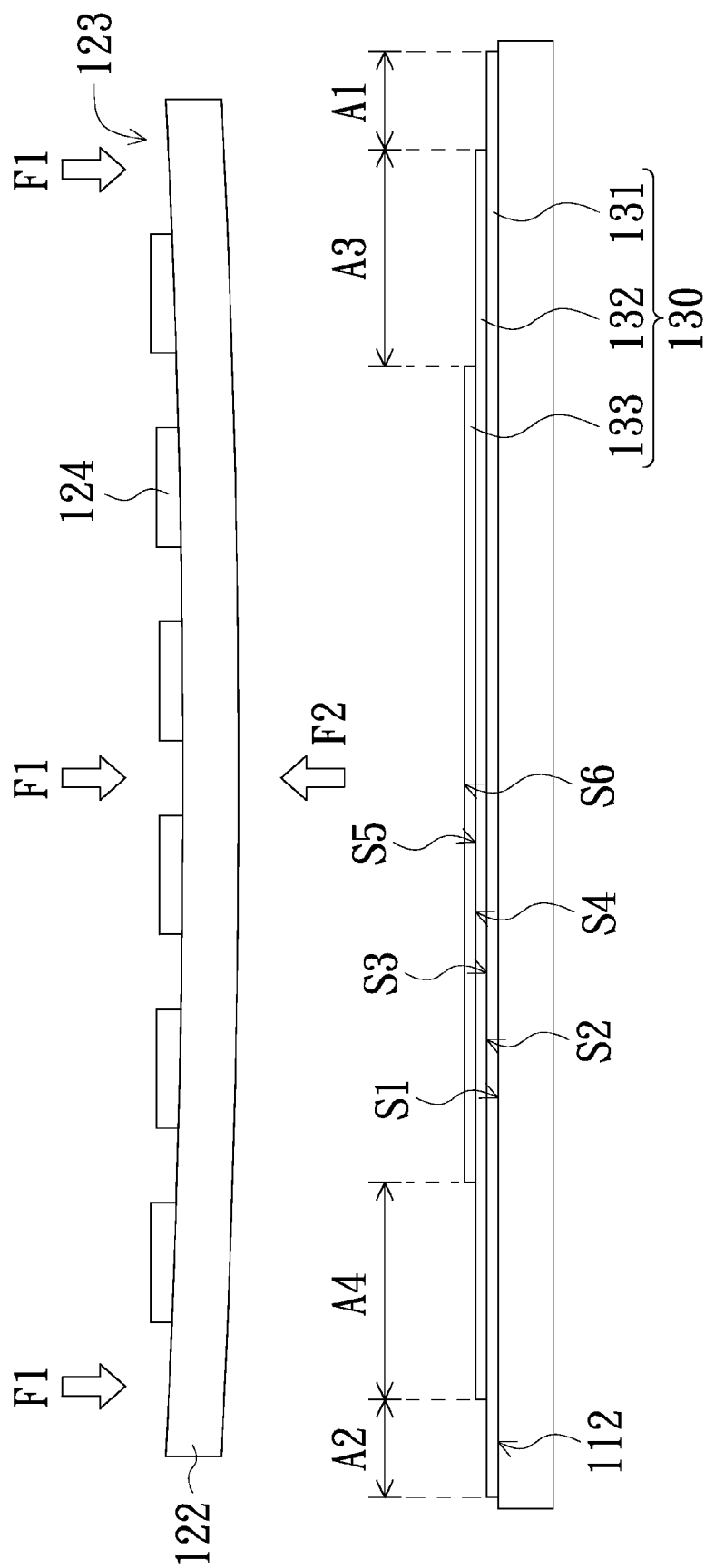


FIG. 3A

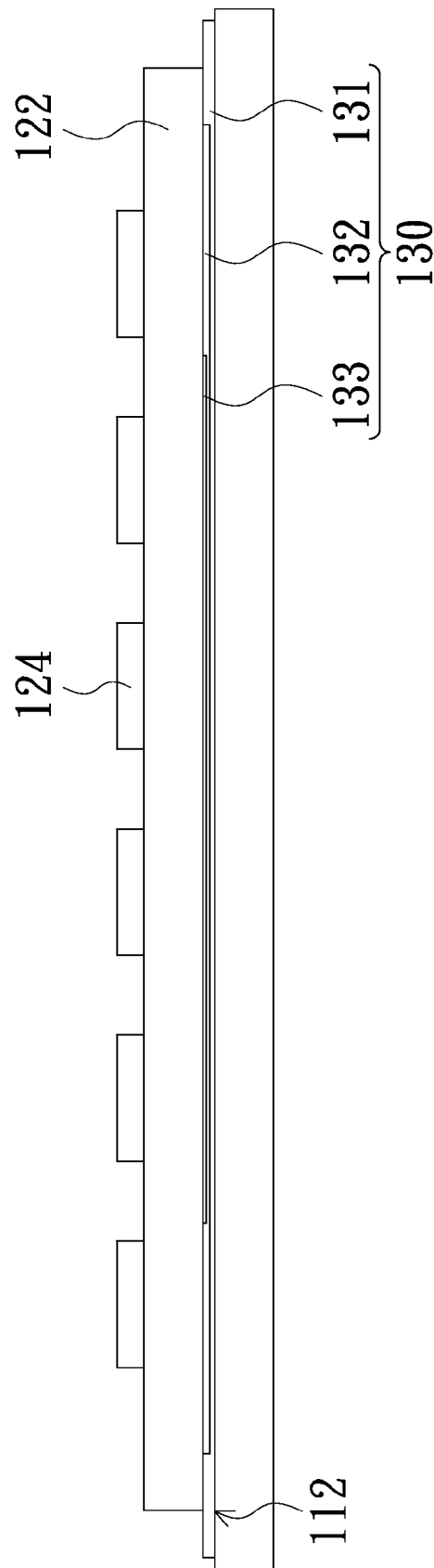


FIG. 3B

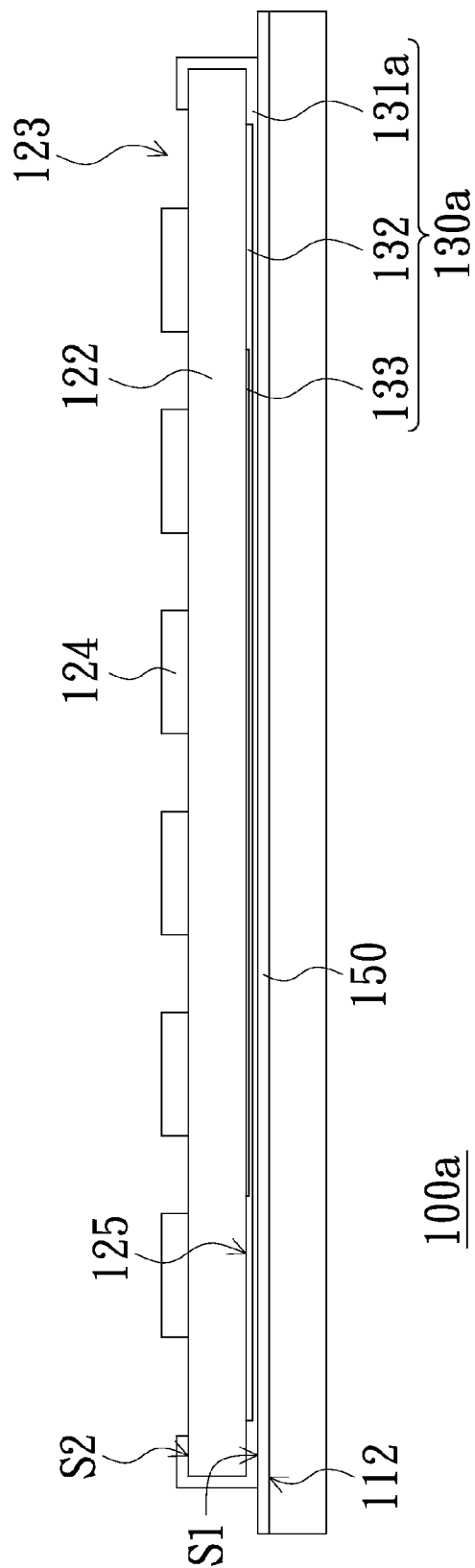


FIG. 4

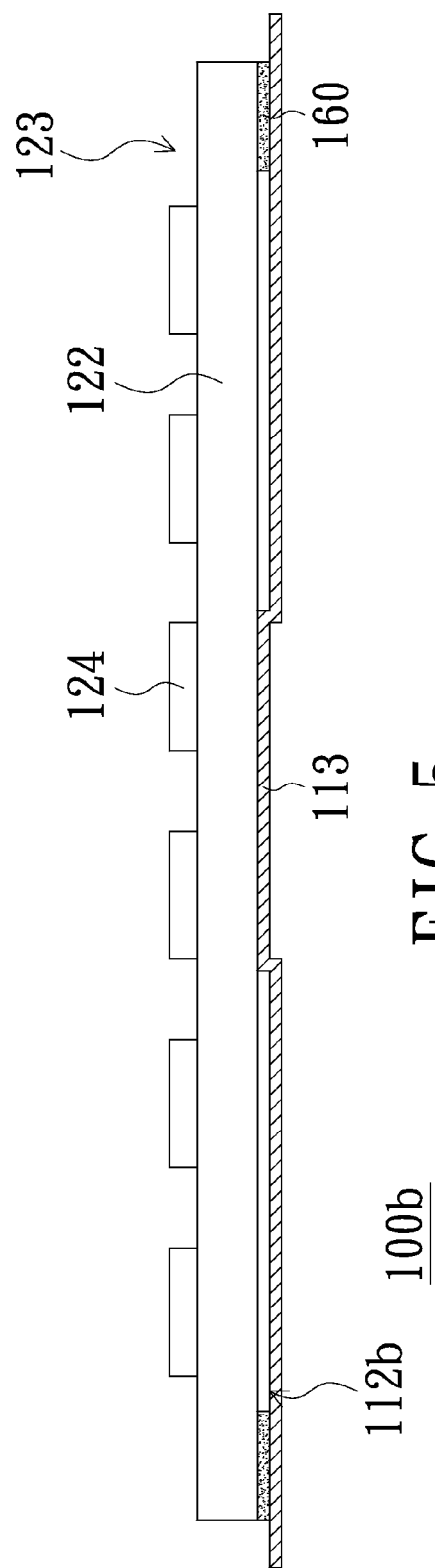


FIG. 5

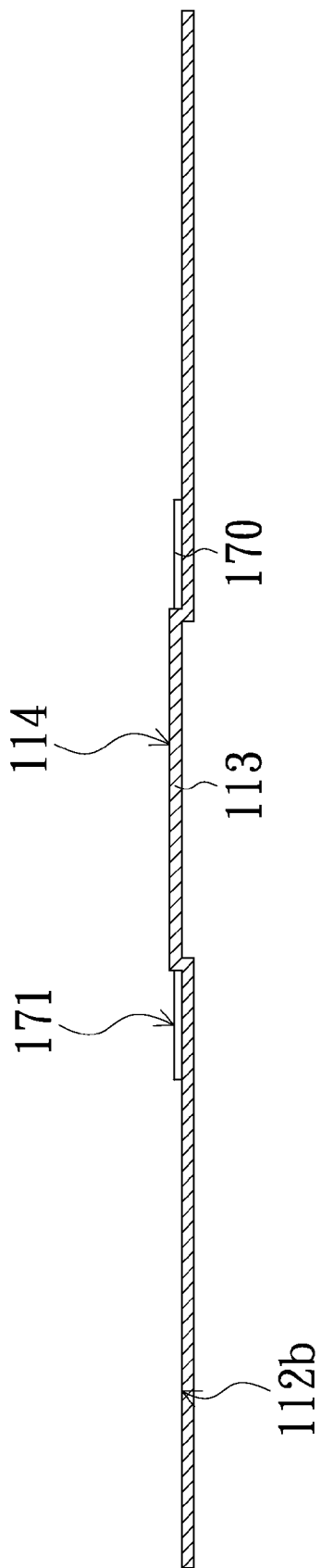


FIG. 6

DISPLAY APPARATUS

TECHNICAL FIELD

The invention relates to a display apparatus, in particularly to a flat panel display.

BACKGROUND

As the manufacturing technology of flat panel displays is more mature, traditional CRT displays have been replaced by the flat panel displays. Currently, typical flat panel displays include liquid crystal displays (LCDs), plasma displays (PDPs), electrophoretic displays and organic light emitting displays (OLEDs). Among these displays, the LCDs have the most popularity.

For satisfying needs of consumers, the LCDs with wide viewing angle and low color shifting have become the mainstream of market. The currently often used wide viewing angle technologies include in plane switching (IPS) and advanced hyper viewing angle (AHVA). However, during the manufacturing of the LCD devices, high heat and high pressure are needed to bond driver chips to the glass substrate of the LCD panel, in such a step, the glass substrate can easily be deformed to bend, which causes abnormal light leakage while the LCD device is in a normally black mode.

SUMMARY

An embodiment of the invention provides a display apparatus including a frame, a panel module and an adjusting pad. The frame has a supporting surface. The panel module includes a substrate and a plurality of chips. The substrate is disposed on the supporting surface and the substrate has a bonding region at a side thereof. The chips are disposed on the bonding region. The chips and the bonding region are located on the supporting surface. The chips and the supporting surface are respectively located at two opposite surfaces of the substrate. The adjusting pad is disposed between the supporting surface and the bonding region. The thickness of the adjusting pad is gradually reduced from the center toward the two sides thereof.

Another embodiment of the invention provides a display apparatus including a frame and a panel module. The frame has a supporting surface and a first adjusting pad protruding from the supporting surface. The panel module includes a substrate and a plurality of chips. The substrate is disposed on the supporting surface and the substrate has a bonding region at a side thereof. The first adjusting pad is located below the bonding region. The chips are disposed on the bonding region. The chips and the supporting surface are respectively located at two opposite surfaces of the substrate.

BRIEF DESCRIPTION OF THE DRAWINGS

The present invention will become more readily apparent to those ordinarily skilled in the art after reviewing the following detailed description and accompanying drawings, in which:

FIG. 1 is a schematic cross sectional view of a display apparatus according to an embodiment of the invention.

FIG. 2 is a schematic top view of a panel module in FIG. 1.

FIG. 3A and FIG. 3B are schematic views showing the panel module is disposed on the supporting surface of the frame.

FIG. 4 is a schematic view of a display apparatus according to another embodiment of the invention.

FIG. 5 is a schematic view of a display apparatus according to another embodiment of the invention.

FIG. 6 is a schematic view showing a frame and a second adjusting frame of a display apparatus according to another embodiment of the invention.

DETAILED DESCRIPTION OF PREFERRED EMBODIMENTS

The present invention will now be described more specifically with reference to the following embodiments. It is to be noted that the following descriptions of preferred embodiments of this invention are presented herein for purpose of illustration and description only. It is not intended to be exhaustive or to be limited to the precise form disclosed.

FIG. 1 is a schematic cross sectional view of a display apparatus according to an embodiment of the invention. FIG. 2 is a schematic top view of a panel module in FIG. 1. Referring to FIG. 1 and FIG. 2, the display apparatus 100 includes a frame 110 and a panel module 120. The frame 110 has a supporting surface 112, and the panel module 120 has a substrate 122 and a plurality of chips 124. The substrate 122 is disposed on the supporting surface 112, and the substrate 122 has a bonding region 123 at a side thereof. The chips 124 are disposed on the bonding region 123. The chips 124 and the bonding region 123 are disposed above the supporting surface 112. The chips 124 and supporting surface 112 are respectively located at above and below of the substrate 122. In this embodiment, the material of the substrate 122 is, for example, glass, but not limited thereto. The substrate 122, for example, includes an active device array (such like a thin film transistor array). The panel module 120 can further include another substrate 126 disposed on the substrate 122. The panel module 120 has the function of displaying images and can be a liquid crystal display module, an organic light emitting display module, an electrophoretic display module and an electrowetting display module, but not limited thereto.

Since the substrate 122 is easily deformed flexure when the chips 124 is being bonded to the bonding region 123, the display apparatus 100 of this embodiment further includes an adjusting pad 130 disposed between the supporting surface 112 and the bonding region 123 for solving the problem of the flexure of the substrate 122. The adjusting pad 130 of this embodiment is detailed below.

FIG. 3A and FIG. 3B are schematic views showing the panel module is disposed on the supporting surface of the frame. In the drawings, only the substrate 122 and the chips 124 are used to represent the panel module 120, and the supporting surface 112 is used to represent the frame 110. As FIG. 3A shows, the adjusting pad 130 of the embodiment is used for leveling the flexural substrate 122. Since after the chips 124 are bonded to the substrate 122, the substrate 122 is affected by stress and is deformed to a shape that the center portion is downwardly bended. Accordingly, the thickness of the adjusting pad 130 is gradually reduced from the center toward the two sides thereof. In other words, the thickness variation of the adjusting pad 130 can be adjusted according to the degree of the flexure of the substrate 122.

The manner of how to make the thickness of the adjusting pad gradually reduce from the center toward the two sides of the invention is not limited. In this embodiment, the adjusting pad 130 has a plurality of base materials (such as a first base material 131, a second base material 132 and a third base material 133) stacked with each other for forming the adjusting pad 130 with the thickness gradually reducing from the center toward the two sides. These base materials are such like adhesive tapes, but not limited thereto. These base materials

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of the adjusting pad **130** are, for example, stripe shaped and sequentially stacked, wherein the second base material **132** is disposed on the first base material **131**, and the third base material **133** is disposed on the second base material **132**. The thickness of each of the base material is determined according to the degree of the flexure of the substrate **122**. Generally speaking, the thickness of the base material is, for example, 0.0025 mm to 0.05 mm, but not limited thereto. The base material can be compressible material such as foam, or can be incompressible material such as polyethylene terephthalate (PET).

Following the above mentioned, for any two of the adjacent base materials, the length of the under base material is longer than the length of the upper base material. In other words, the length of the first base material **131** is longer than the length of the second base material **132**, and the length of the second base material **132** is longer than the length of the third base material **133**. Besides, for any two adjacent substrates, two side of the under base material has regions which are not overlapped by the upper substrate. And the regions have the same dimensions. That is, the two regions **A1**, **A2** of the first base material **131** which are not overlapped by the second base material **132** have the same dimensions. The two regions **A3**, **A4** of the second base material **132** which are not overlapped by the third base material **133** have the same dimensions.

The first base material **131** has a first surface **S1** and a second surface **S2** opposite to each other. The second base material **132** has a third surface **S3** and a fourth surface **S4** opposite to each other. The third base material **133** has a fifth surface **S5** and a sixth surface **S6** opposite to each other. The first surface **S1** is adhesive and is attached to the supporting surface **112**. The second surface **S2** is adhesive, and the third surface **S3** is attached to the second surface **S2**. The fourth surface **S4** and the sixth surface **S6** are nonadhesive. The fifth surface **S5** is adhesive and is attached to the fourth surface **S4**.

When a force **F1** is exerted on the panel module to fix it on the supporting surface **112** of the frame **110**, the thicker center part of the adjusting pad **130** will first contact with the substrate **122**. During the time that the panel module **120** is continuously pressed, the thicker part of the adjusting pad **130** provides a reactive force **F2** upwardly pushing the downwardly flexural part of the substrate **122**, thus leveling the substrate **122**. Therefore, as FIG. 3B shows, when the two sides of the substrate **122** are attached to the exposed second surface **S2** of the first base material **133**, the flatness of the substrate **122** is well improved. The downgrade of the display quality of the display apparatus **100** (as shown in FIG. 1) caused from the flexure of the substrate **122** can be prevented.

In this embodiment, at least one of the chips **124** has a projection which is completely projected onto the top substrate of the adjusting pad **130**. In other words, the length of the third base material **133** is larger than or equal to the length of the single chip **124**, and the width of the third base material **133** is larger than or equal to the width of the single chip **124**. Besides, all the chips **124** are disposed over the second base material **132**. In addition, the first base material **133** on the bottom can use light shielding material as a light shielding layer for preventing light leakage from the edge of the substrate **122**.

It should be mentioned that although the adjusting pad **130** has three base materials in this embodiment, however, the number of the base materials is not limited thereto. The number of the base materials can be adjusted according to the degree of the flexure of the substrate **122**. Besides, since the

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frame **110** of the invention is a component used for carrying the panel module **120**, the specific structure of the frame is not limited.

Referring to FIG. 1, in an embodiment that the panel module **120** is a non-self emitting panel module (such as a liquid crystal panel module), the display apparatus **100** can further include a backlight module **140** disposed below the panel module **120** for providing the light needed by the panel module **120**. The backlight module **140** can include light emitting devices, light guiding plates and optical films. In other embodiment that the panel module **120** is a self emitting panel module (such as an organic light emitting panel module), or a reflective panel module (such as an electrophoretic panel module or an electrowetting panel module), the backlight module **140** can be omitted. Besides, in addition to dispose the adjusting pad **130** between the supporting surface **112** and the bonding region **123**, in case the flexure is occurred at the other side of the substrate **122**, the adjusting pad **130** can be disposed between the flexural side portion of the substrate **122** and the supporting surface **112**.

FIG. 4 is a schematic view of a display apparatus according to another embodiment of the invention. Referring to FIG. 4, which is similar to FIG. 3B, only the substrate **122** and the chips **124** are used to represent the panel module, and the supporting surface **112** is used to represent the frame. The structure and advantages of display apparatus **100a** of this embodiment is similar to that of the display apparatus **100** of the above mentioned embodiment. The difference is that the first surface **S1** of the first base material **133a** of the adjusting pad **130a** is nonadhesive. A double sided tape **150** is disposed between the first surface **S1** of the adjusting pad **130a** and the supporting surface **112** for attaching the first surface **S1** to the supporting surface **112**. Besides, two ends of the first base material **133a** are, for example, further bended to the bonding region **123**, and the second surface **S2** of the first base material **133a** is, for example, adhered to the bonding region **123** and the back surface **125** of the substrate **122**.

FIG. 5 is a schematic view of a display apparatus according to another embodiment of the invention. Referring to FIG. 5, which is similar to FIG. 3B, only the substrate **122** and the chips **124** are used to represent the panel module, and the supporting surface **112b** is used to represent the frame. The structure and advantages of display apparatus **100b** of this embodiment is similar to that of the display apparatus **100** of the above mentioned embodiment. The difference is that the frame of the embodiment has a first adjusting pad **113** protruding from the supporting surface **112b**. The first adjusting pad **113** is located between the supporting surface **112b** and the bonding region **123**. The frame is, for example, a metal frame. The first adjusting pad **113** can be formed by punching the frame. The function of the first adjusting pad **113** is similar to the function of the above mentioned adjusting pad **130** and is not repeated herein. Besides, the display apparatus **100b** can further include an adhering portion **160** attached between the supporting surface **112b** and the substrate **122**. The adhering portion **160** is located at two sides of the first adjusting pad **113**. The adhering portion **160** is, for example, a double sided tape for fixing the substrate **122** to the supporting surface **112b**. Besides, the display apparatus **100b** can include the above mentioned backlight module according to the type of the panel module.

In another embodiment, as FIG. 6 shows, in addition to directly form the first adjusting pad **113** on the frame, a second adjusting pad **170** can further be attached to the supporting surface **112b**. The second adjusting pad **170** is located at two sides of the first adjusting pad **113** and bears against the first adjusting pad **113**. A top surface **171** of the second

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adjusting pad 170 facing the substrate is lower than a top surface 114 of the first adjusting pad 113 facing the substrate. In other words, the thickness or height of the second adjusting pad 170 is smaller than the thickness or height of the first adjusting pad 113. Considering the degree of the flexure of the substrate, a third adjusting pad (not shown) having thickness thinner than the second adjusting pad 170 can be disposed adjacent to two sides of the second adjusting pad 170. Moreover, a fourth adjusting pad (not shown) having thickness thinner than the third adjusting pad can be disposed adjacent to two sides of the third adjusting pad. Alternatively, a plurality of base materials can be stacked as the above mentioned embodiment to form the second adjusting pad with different thickness.

In conclusion, in the display apparatus of the invention, the adjusting pad can be used to bear against the flexural portion of the substrate and level the substrate, such that the downgrade of the display quality of the display apparatus caused from the flexure of the substrate can be prevented.

While the invention has been described in terms of what is presently considered to be the most practical and preferred embodiments, it is to be understood that the invention needs not be limited to the disclosed embodiment. On the contrary, it is intended to cover various modifications and similar arrangements included within the spirit and scope of the appended claims which are to be accorded with the broadest interpretation so as to encompass all such modifications and similar structures.

What is claimed is:

1. A display apparatus comprising:

a frame having a supporting surface;

a panel module comprising:

a substrate disposed on the supporting surface and the substrate having a bonding region at a side thereof,

a plurality of chips disposed on the bonding region, wherein the chips and the bonding region are located on the supporting surface, and the chips and the supporting surface are respectively located at two opposite surfaces of the substrate; and

an adjusting pad disposed between the supporting surface and the bonding region, and a thickness of the adjusting pad being gradually reduced from a center of the adjusting pad toward two sides thereof, wherein the adjusting pad comprises a plurality of base materials, a length of

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an under base material is longer than a length of an upper base material for any two adjacent base materials, the base materials comprises a first layer, the first layer has a first surface and a second surface opposite to each other, the first surface faces the supporting surface, the second surface is adhesive, and a back surface of the substrate is attached to a part of the second surface, wherein said under base material is said first layer.

2. The display apparatus as claim 1, wherein the base materials are stripe shaped and sequentially stacked.

3. The display apparatus as claim 2, wherein the under base material has two side regions being not overlapped by the upper base material for any two adjacent base materials.

4. The display apparatus as claim 2, wherein at least one of the chips has a projection being completely projected onto the top base material of the adjusting pad.

5. The display apparatus as claim 2, wherein the base materials at least has a second layer and a third layer, the second layer is disposed on the first layer, and the third layer is disposed on the second layer, the second layer has a third surface and a fourth surface opposite to each other, the third layer has a fifth surface and a sixth surface opposite to each other, the third surface is attached to the second surface, the fourth surface and the sixth surface are nonadhesive, and the fifth surface is adhesive and is attached to the fourth surface.

6. The display apparatus as claim 5, wherein the first surface is adhesive and is attached to the supporting surface.

7. The display apparatus as claim 5, further comprising a double sided tape disposed between the first surface and the supporting surface, wherein the first surface is nonadhesive, and the first surface is attached to the supporting surface with the double sided tape.

8. The display apparatus as claim 7, wherein two ends of the first base material are further bent to the bonding region and the second surface is attached to the bonding region.

9. The display apparatus as claim 5, wherein the chips are completely disposed over the second base material.

10. The display apparatus as claim 2, wherein the bottom base material is a light shielding layer.

11. The display apparatus as claim 2, wherein the base materials are adhesive tapes.

12. The display apparatus as claim 1, further comprising a backlight module disposed below the panel module.

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